AMENDMENTS

In The Specification:

Please amend the specification as follows.

[0016] As conventionally arranged, tie bars 208 connecting the die pad 204 to the leadframe 200 support the die pad 204. The tie bars 208 prevent the die pad 204 from bending when an encapsulating process is subsequently performed. A portion 209 of the tie bars 208 further may be downwardly bent to down-set the die pad 204.

In The Claims:

1. (Amended) A packaging structure integrating passive devices, comprising:

a leadframe, wherein the leadframe includes a plurality of first leads defining a chip-bonding region, a plurality of second leads extending and terminating in a plurality of contact pads within the chip-bonding region, and a die pad located at a sideways biased position in the chip-bonding region;

a chip bonded onto the die pad;

at least a passive device mounted between and connected to the contact pads;

a plurality of bonding wires electrically connecting the chip, the passive device, and the first and second leads to one another; and

an encapsulant material encapsulating the chip, the passive device, and the bonding wires.

8. (Amended) A leadframe structure suitable for use in a chip packaging structure, the leadframe structure comprising:

a plurality of first leads defining a chip-bonding region in the leadframe structure;

a plurality of second leads extending and terminating in a plurality of contact pads within the chip-bonding region; and

a die pad arranged at a sideways biased position in the chip-bonding region.

10. (Amended) A packaging structure integrating passive devices, comprising:

a leadframe, wherein the leadframe includes a plurality of first leads defining a chip-bonding region, a plurality of second leads extending and terminating in a plurality of contact pads within the chip-bonding region, and a die pad located at a sideways biased position in the chip-bonding region;

an adhesive tape bonded to bottom surfaces of the contact pads;

a chip bonded onto the die pad;

at least a passive device mounted between and connected to the contact pads;

a plurality of bonding wires electrically connecting the chip, the passive device, and the leads to one another; and

an encapsulant material encapsulating the chip, the passive device, and the bonding wires.

15. (Amended) A leadframe structure suitable for use in a chip packaging structure, the leadframe structure comprising:

a plurality of first leads defining a chip-bonding region in the leadframe structure;

a plurality of second leads extending and terminating in a plurality of contact pads within the chip-bonding region;

an adhesive tape bonded to bottom surfaces of the contact pads; and

a die pad arranged at a sideways biased position in the chip-bonding region.